

**Features**

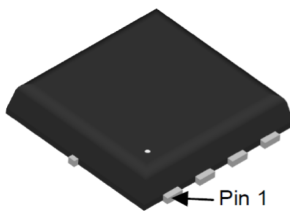
- Low FOM  $R_{DS(on)} \times Q_{gd}$
- 100% avalanche tested
- Easy to use/drive
- RoHS compliant

**Application**

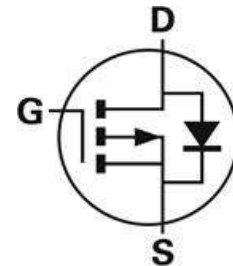
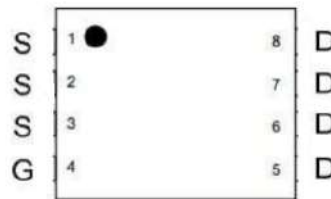
- Power Switch Circuit of Adaptor and Charger
- Battery Protection Charge/Discharge
- Notebook AC-in Load Switch

**Product Summary**

$V_{DS}$	-30	V
$R_{DS(on),TYP@ V_{GS}=10V}$	6.4	m $\Omega$
$I_D$	-55	A



PDFN3\*3-8

**Absolute Maximum Ratings**  $T_A = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Values	Unit
Drain-Source voltage( $V_{GS}=0V$ )	$V_{DS}$	-30	V
Continuous Drain Current <sup>2)</sup>	$I_D$	$T_C = 25^\circ\text{C}$	-55
		$T_C = 100^\circ\text{C}$	-34.6
Pulsed Drain Current <sup>3)</sup>	$I_{D,pulse}$	-220	A
Gate-Source Voltage	$V_{GSS}$	$\pm 25$	V
Single Pulse Avalanche Energy	$E_{AS}$	200	mJ
Power Dissipation	$P_D$	31.2	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55~+150	$^\circ\text{C}$

**Thermal Resistance**

Parameter	Symbol	Max.	Unit
Thermal Resistance, Junction-to-Case	$R_{thJC}$	4	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	35	$^\circ\text{C/W}$

**Notes**

- 1)  $L=0.5\text{mH}, V_{DD}=-15V, \text{Start } T_J=25^\circ\text{C}$
- 2) Limited by maximum junction temperature.
- 3) Repetitive Rating: Pulse width limited by maximum junction temperature.

Electrical Characteristics $T_J = 25^\circ\text{C}$ , unless otherwise noted						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -30V$ $V_{GS} = 0V, T_J = 25^\circ\text{C}$	--	--	-1	$\mu A$
		$V_{DS} = -24V$ , $V_{GS} = 0V, T_J = 125^\circ\text{C}$	--	--	-100	
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 25V$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1.2	-1.8	-2.5	V
Drain-Source On-State-Resistance	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -20A$	--	6.4	8	$m\Omega$
		$V_{GS} = -4.5V, I_D = -10A$	--	10.5	13	$m\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V$ , $V_{DS} = -15V$ $f = 1.0\text{MHz}$	--	3482	--	$\mu F$
Output Capacitance	$C_{oss}$		--	400	--	
Reverse Transfer Capacitance	$C_{rss}$		--	309	--	
Total Gate Charge	$Q_g$	$V_{DS} = -15V, I_D = -10A$ $V_{GS} = -10V$	--	61	--	nC
Gate-Source Charge	$Q_{gs}$		--	12	--	
Gate-Drain Charge	$Q_{gd}$		--	10	--	
Gate Plateau Voltage	$V_{Plateau}$		--	3.1	--	V
Turn-on Delay Time	$t_{d(on)}$	$V_{DS} = -15V, V_{GS} = -10V$ $R_G = 3\Omega, I_D = -10A$	--	19	--	ns
Turn-on Rise Time	$t_r$		--	33	--	
Turn-off Delay Time	$t_{d(off)}$		--	38	--	
Turn-off Fall Time	$t_f$		--	15	--	
<b>Drain-Source Body Diode Characteristics</b>						
Body Diode Forward Voltage	$V_{SD}$	$T_J = 25^\circ\text{C}, I_{SD} = -10A$ , $V_{GS} = 0V$	--	--	-1.2	V
Continuous Diode Forward Current	$I_S$		--	--	-55	A
Reverse Recovery Time	$t_{rr}$	$I_F = -10A, di_F/dt = -100A/\mu s$	--	45	--	ns
Reverse Recovery Charge	$Q_{rr}$		--	29	--	nC



Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

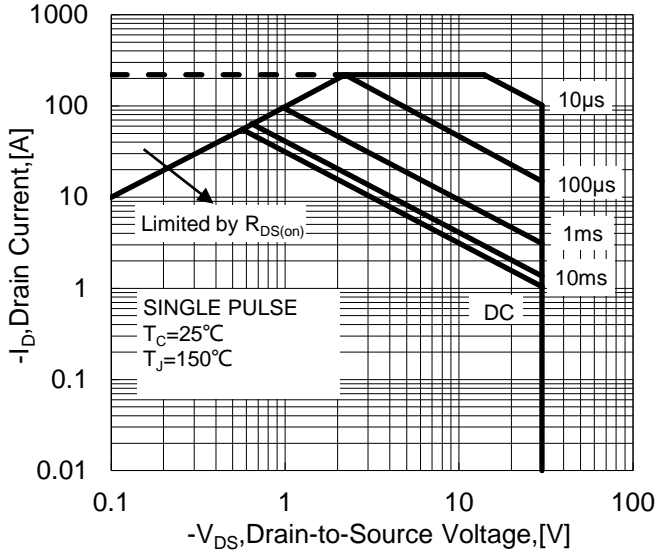


Figure 1. Maximum Safe Operating Area

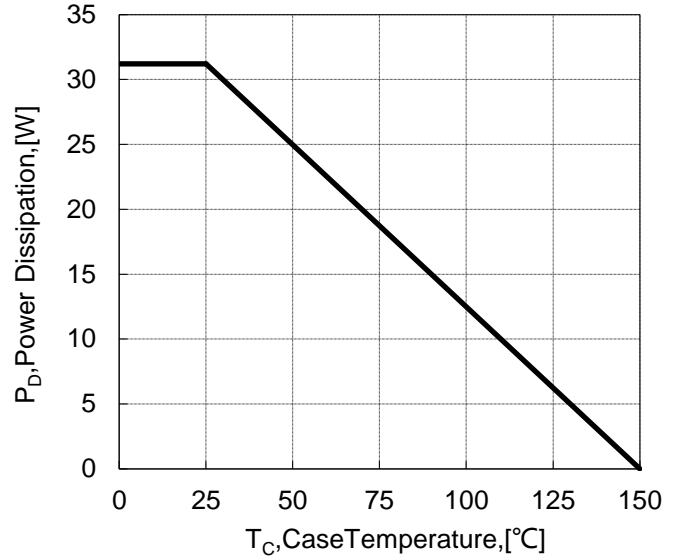


Figure 2. Maximum Power Dissipation vs Case Temperature

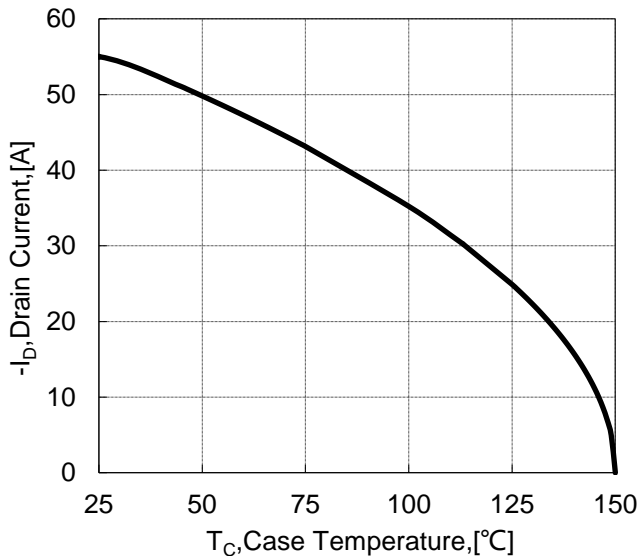


Figure 3. Maximum Continuous Drain Current vs Case Temperature

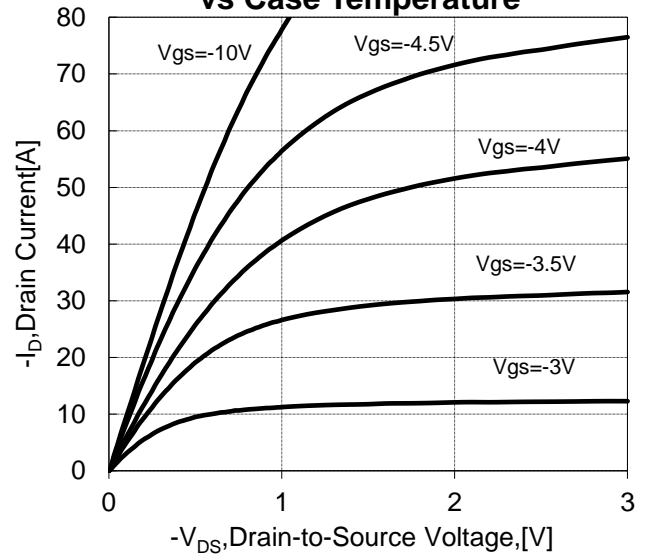


Figure 4. Typical output Characteristics

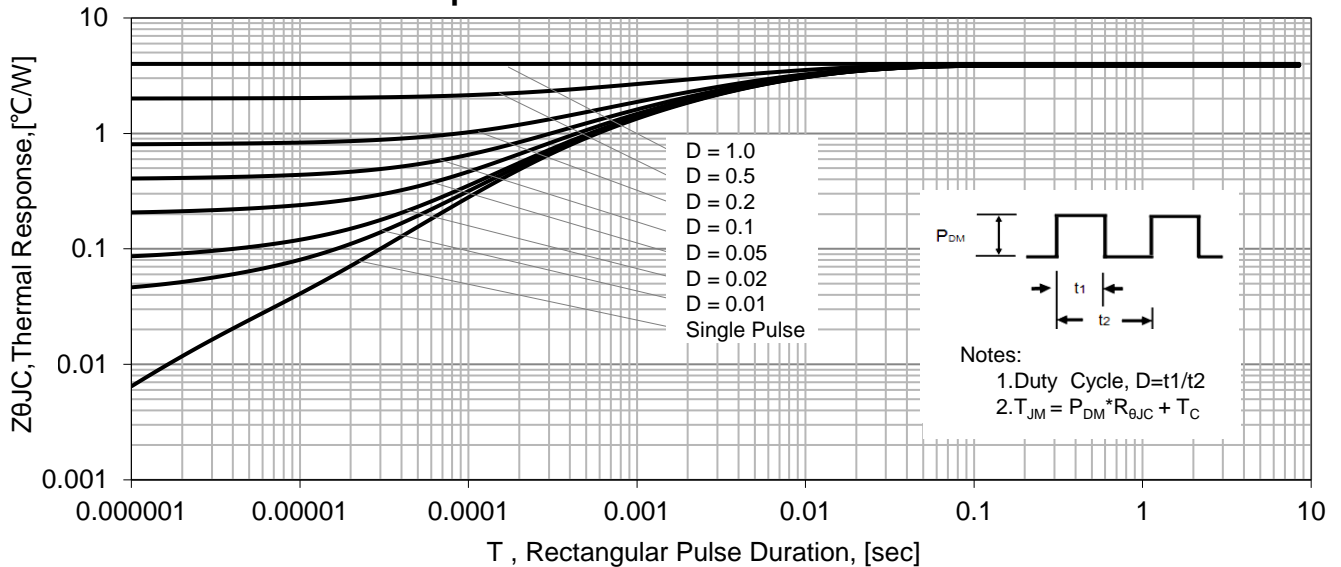


Figure 5 Maximum Effective Thermal Impedance , Junction to Case



Typical Characteristics  $T_j = 25^\circ\text{C}$ , unless otherwise noted

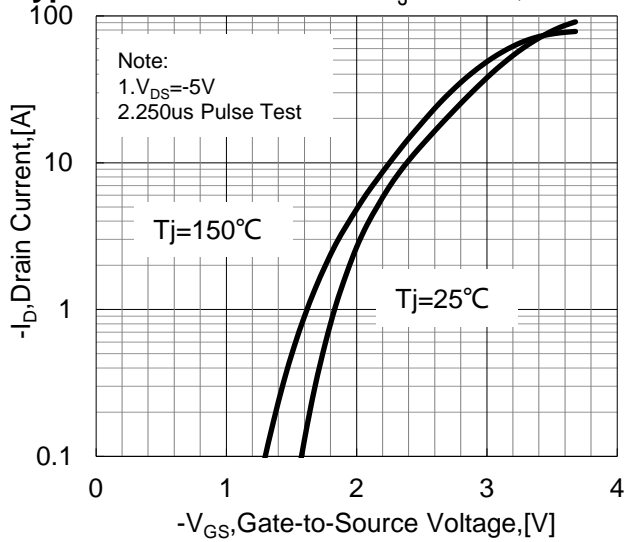


Figure 6 Typical Transfer Characteristics

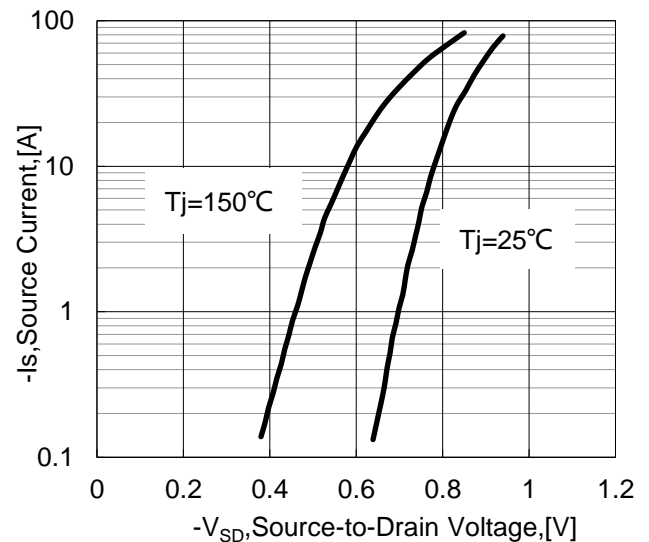


Figure 7 Typical Body Diode Transfer Characteristics

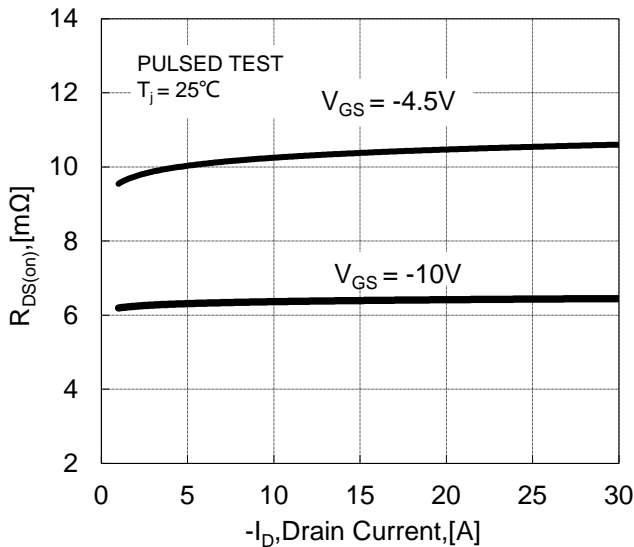


Figure 8. Drain-to-Source On Resistance vs Drain Current

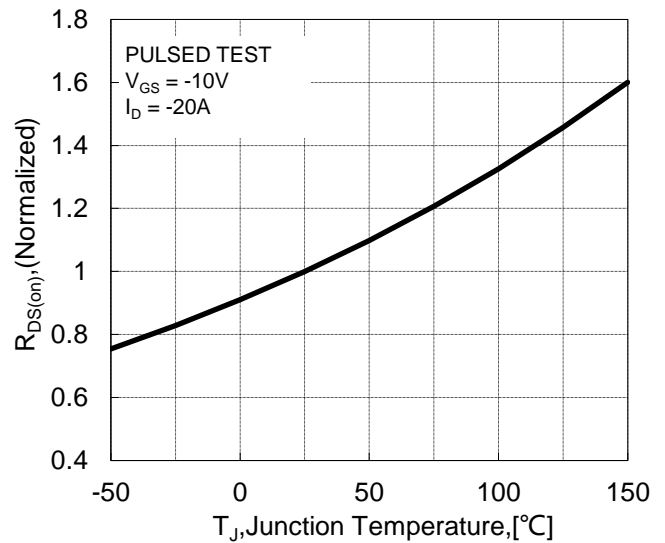


Figure 9. Normalized On Resistance vs Junction Temperature

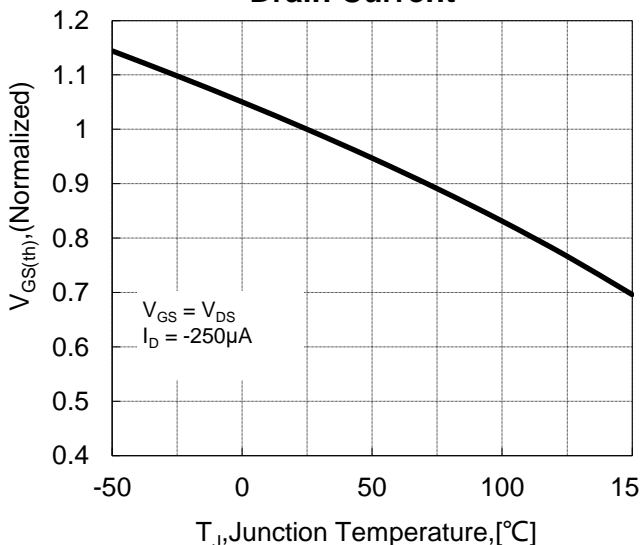


Figure 10. Normalized Threshold Voltage vs Junction Temperature

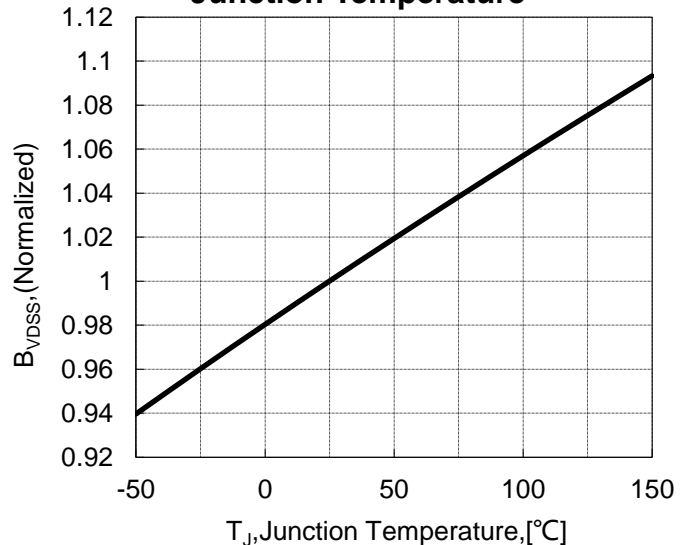
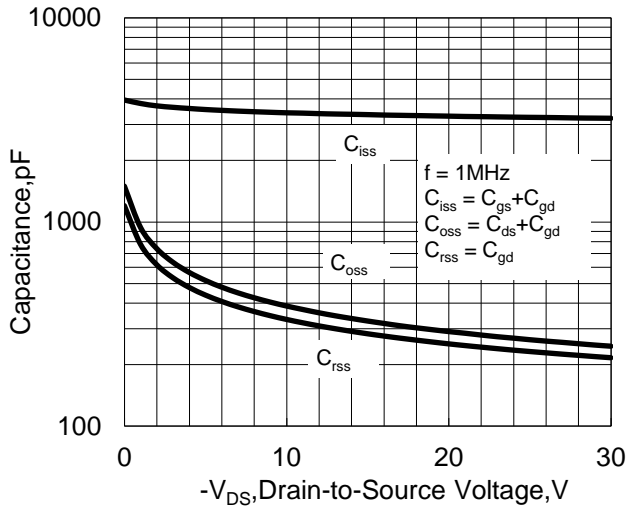
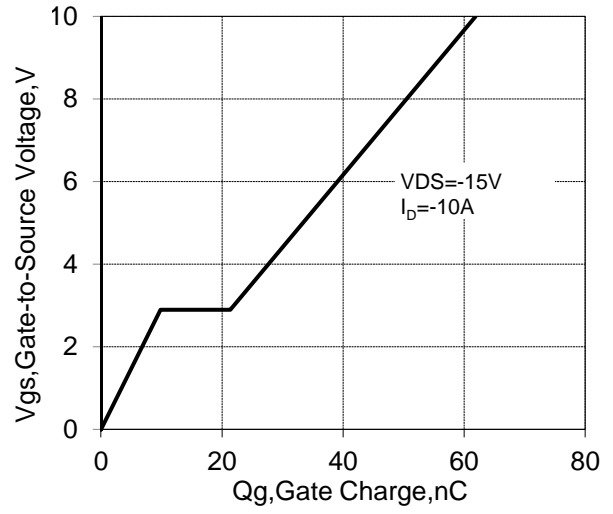


Figure 11. Normalized Breakdown Voltage vs Junction Temperature

**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted



**Figure 12. Capacitance Characteristics**



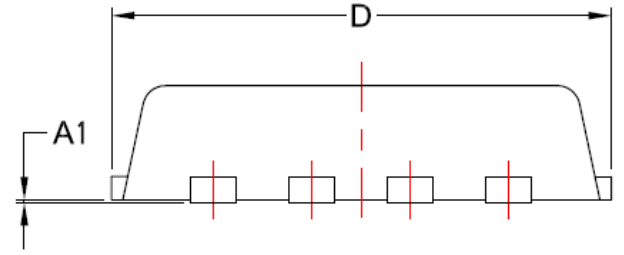
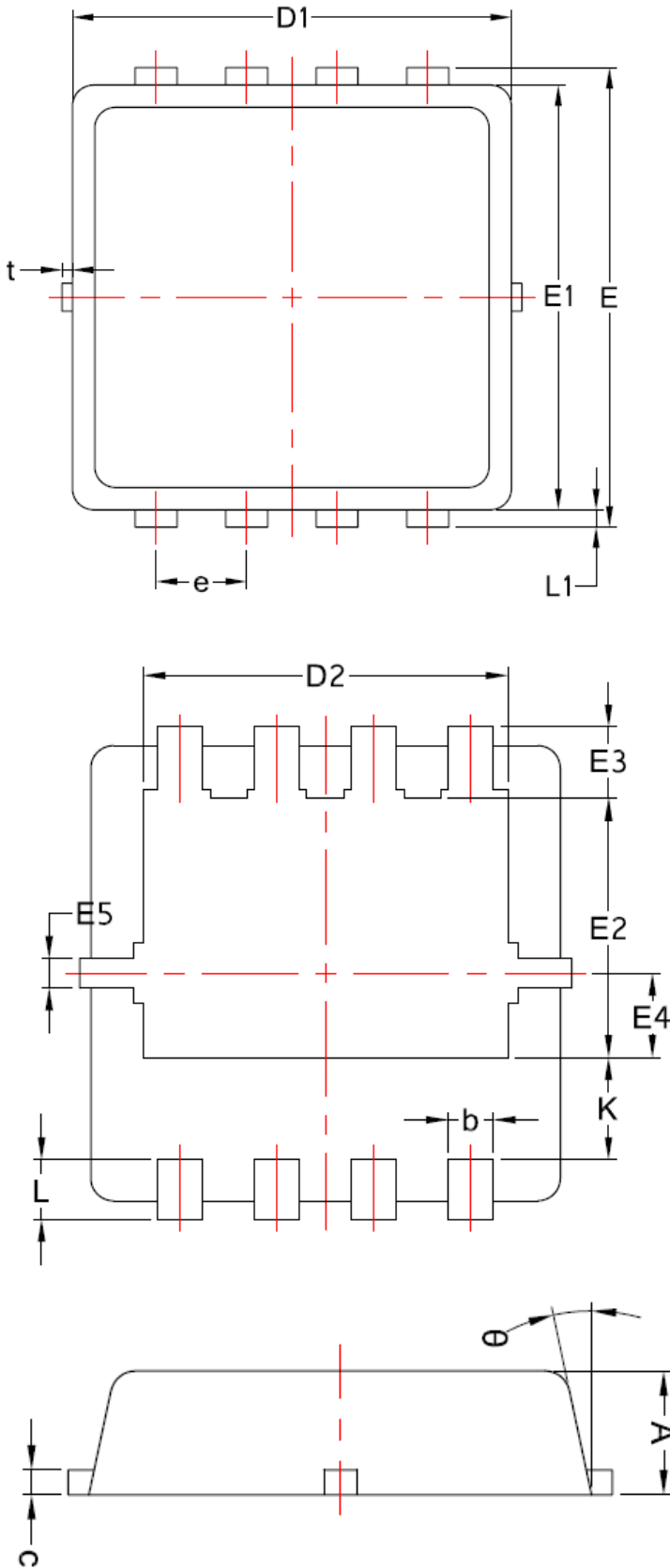
**Figure 13 Typical Gate Charge vs Gate to Source Voltage**

## Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
ASDM30P11TD-R	30P11J	PDFN3*3-8	Tape&Reel	5000

PACKAGE	MARKING
PDFN3*3-8	<div style="border: 1px solid black; padding: 10px; display: inline-block;"> <p style="text-align: center;">30P11J</p> <p style="text-align: center;">□□□□□□□□ → Date Code</p> </div>

**PDFN3\*3\_8 Package**



SYMBOL	COMMON		
	MM		
	MIN	NOM	MAX
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
θ	10°	12°	14°

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